

**AMENDMENTS TO THE SPECIFICATION:**

Please replace the paragraph beginning at page 6, line 20, with the following amended paragraph:

In those figures, reference number 5 designates an integrated circuit device, 1 denotes a thinned silicon (Si) substrate, and 2 indicates an integrated circuit such as a memory circuit or a logic circuit formed on the front surface (as a first surface) of the substrate 1. Reference number 3 designates each of a plurality of (unlined) connection holes which penetrate the substrate 1 and the integrated circuit 2, and 4 designates each connection pile formed in a corresponding (unlined) connection hole 3. The connection pile 4 is made of a conductive material such as cupper (Cu) (i.e. the connection pile is in direct contact with the integrated circuit 2).